

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|--------|-----------------------|---|------------------|---------|------------------|
| L1 | 118219 | cmos | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 10:58 |
| L2 | 385 | cmos and microchannel | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 10:59 |
| L3 | 4 | 2 and microheater | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 10:59 |
| L4 | 4 | 2 and micro\$heater | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 10:59 |
| L5 | 27 | 2 and heater | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:00 |
| L6 | 23 | 5 and fluid | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:05 |
| L7 | 39 | 2 and mems | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:07 |
| L8 | 2 | 7 and conductor | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:07 |

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|-----|------|-----------------------|---|----|-----|------------------|
| L9 | 25 | 7 and ion | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:08 |
| L10 | 0 | 7 and ion near boron | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:08 |
| L11 | 0 | 7 and ion near2 boron | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:08 |
| L12 | 0 | 2 and ion near2 boron | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:08 |
| L13 | 2555 | 1 and ion near2 boron | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:33 |
| L14 | 1381 | 1 and ion near boron | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:09 |
| L15 | 73 | 14 and heater | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:09 |
| L16 | 68 | 15 and conduct\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:31 |

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| L17 | 9 | 16 and boron near doped | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:14 |
| L18 | 0 | 16 and boron near doped near2 substrate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:16 |
| L19 | 29 | 14 and boron near doped near2 substrate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:15 |
| L20 | 0 | 15 and boron near doped near2 substrate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:15 |
| L21 | 0 | 15 and boron near doped near5 substrate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:15 |
| L22 | 0 | 16 and boron near doped near2 wafer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:27 |
| L23 | 4 | 16 and boron near doped near2 silicon | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:16 |
| L24 | 2 | 14 and boron near doped near2 wafer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:43 |

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| L25 | 0 | 15 and boron near doped near2 wafer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:18 |
| L26 | 7 | 1 and 219/548 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:21 |
| L27 | 52 | micro\$hotplate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:56 |
| L28 | 0 | 27 and boron near doped near2 wafer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:27 |
| L29 | 43 | 27 and conduct\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:45 |
| L30 | 12 | 27 and conductor | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:38 |
| L31 | 0 | 30 and conductor near2 boron near ion | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:33 |
| L32 | 0 | 27 and ion near2 boron | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:33 |

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| L33 | 0 | 30 and glass adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:35 |
| L34 | 3342806 | 30 and glass nearj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:40 |
| L35 | 0 | 30 and glass near2 layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:36 |
| L36 | 2 | 30 and microheater | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:36 |
| L37 | 11 | 30 and glass | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:40 |
| L38 | 1 | 30 and glass near boro\$8 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:41 |
| L39 | 0 | 27 and boron near doped near2 wafer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:43 |
| L40 | 6 | 27 and conduct\$3 near polymer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:45 |

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| L41 | 18 | 27 and quartz | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:57 |
| L42 | 10 | 37 and quartz | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/03/11 11:57 |